

Material Declaration Report



Package Type:	TSSOP 24L (4.4mm)
Pericom Package Code:	L24(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	87.000
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10-20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	6/4/2008

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	53.361	OSE	Silica Fused	60676-86-0	89.800	47.9181
			Epoxy Resin	Proprietary	5.000	2.6680
			Phenolic Resin	Proprietary	4.000	2.1344
			Others	Proprietary	1.000	0.5336
			Carbon Black	1333-86-4	0.200	0.1067
		SPEL	Silica Fused	60676-86-0	88.000	46.9576
			Epoxy Resin	Proprietary	5.000	2.6680
			Phenolic Resin	Proprietary	4.500	2.4012
			Epoxy, Cresol Novolac	29690-82-2	2.000	1.0672
			Carbon Black	1333-86-4	0.500	0.2668
LEADFRAME	29.539		Copper	7440-50-8	95.140	28.1030
			Nickel	7440-02-0	3.200	0.9452
			Silver	7440-22-4	0.760	0.2245
			Silicon	7440-21-3	0.725	0.2142
			Magnesium	7439-95-4	0.175	0.0517
SILICON DIE	1.175		Silicon (Si)	7440-21-3	99.192	1.1654
			Non-hazardous Metal	Proprietary	0.808	0.0095
DIE ATTACH EPOXY	0.191	OSE	Silver	7440-22-4	76.000	0.1448
			Acrylic Resin	Proprietary	8.000	0.0152
			Acrylate	Proprietary	5.500	0.0105
			Polybutadiene derivative	Proprietary	5.500	0.0105
			Epoxy resin	Proprietary	2.500	0.0048
			Additive	Proprietary	1.000	0.0019
			Butadiene copolymer	Proprietary	1.000	0.0019
			Peroxide	Proprietary	0.500	0.0010
		SPEL	Silver	7440-22-4	80.000	0.1524
			Epoxy Resin	9003-36-5	10.000	0.0191
			Diluent	26447-14-3	6.000	0.0114
			Hardener	620-92-8	3.250	0.0062
			Dicyandamide	461-58-5	0.750	0.0014
GOLD WIRE	0.515		Gold(Au)	7440-57-5	99.990	0.5151
			Impurities	-	0.010	0.0001
SOLDER PLATING	2.220		Tin (Sn)	7440-31-5	99.990	2.2197
			Impurity	-	0.010	0.0002

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium																	
	<table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td><1000ppm</td> <td><1000ppm</td> <td><1000ppm</td> <td><100ppm</td> <td><1000ppm</td> <td><1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O
Pb	Hg	Cr+6	Cd	PBB	PBDE													
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm													
O	O	O	O	O	O													
<p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>																		